



Material Content Data Sheet



Sales Product Name		BSD235C H6327		Issued		29. August 2013		
MA#		MA000958634						
Package		PG-SOT363-6-1		Weight*		6.89 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.128	1.86	1.86	18578	18578
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		84	
	non noble metal	titanium	7440-32-6	0.003	0.04		418	
	non noble metal	chromium	7440-47-3	0.009	0.13		1255	
wire	non noble metal	copper	7440-50-8	2.869	41.66	41.84	416690	418447
	non noble metal	copper	7440-50-8	0.010	0.15	0.15	1503	1503
	encapsulation	organic material	carbon black	1333-86-4	0.029	0.42		4237
encapsulation	plastics	epoxy resin	-	0.627	9.11		91097	
	inorganic material	silicondioxide	60676-86-0	2.261	32.84	42.37	328371	423705
leadfinish	non noble metal	tin	7440-31-5	0.213	3.10	3.10	30968	30968
plating	noble metal	silver	7440-22-4	0.056	0.82	0.82	8164	8164
solder	non noble metal	tin	7440-31-5	0.139	2.02		20220	
	noble metal	gold	7440-57-5	0.540	7.84	9.86	78415	98635
*deviation	< 10%		Sum in total:			100,00		1000000

Important Remarks:

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Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com